

## Technical Note

## General-purpose CMOS Logic IC Series (BU4S,BU4000B Series) Single Gate CMOS Logic ICs <Analog Switch>



No. 09050JAT02

## BU4S66G2

#### Description

The BU4S66G2 is a 1ch analog switch IC encapsulated in an SSOP5 package, and can replace 1 circuit of the general-purpose CMOS two-way analog switch BU4066B IC.

#### Features

- 1) Low power consumption
- 2) Surface mount package (SSOP5)
- 3) Broad operating supply voltage range: 3V-16V
- 4) L-TTL2 and LS-TTL1 inputs can be driven directly
- 5) Function compatible with BU4066BC series (1ch).
- 6) Excellent linearity

#### Applications

Can be used as a digital/analog switch, ON/OFF switch, or changeover switch in a high speed line, with no deterioration of the analog signals. Connection to a low impedance circuit is possible, due to the low ON resistance.

#### Lineup



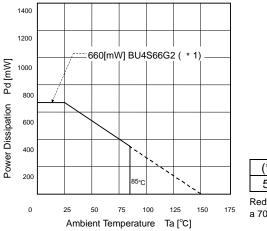
#### Absolute Maximum Ratings

Parameter	Symbol	Limit	Unit
Power Supply Voltage	VDD	-0.3 to 18	V
Supply Current	lin	±10	mA
Operating Temperature	Topr	-40 to 85	S
Storage Temperature	Tstg	-55 to 150	S
Input Voltage	VIN	-0.3 to VDD+0.3	V
Maximum Junction Temperature	Tjmax	150	°C

#### Recommended Operating Conditions

Parameter	Symbol	Limit	Unit
Operating Power Supply	VDD	3 to 16	V
Input Voltage	VIN	0 to VDD	V

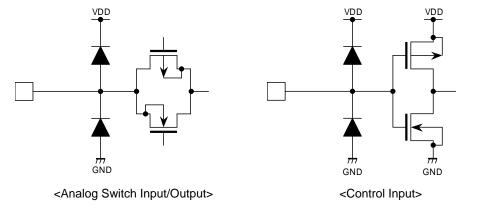
#### •Thermal Derating Curve



	(*1)	Unit	
	5.3	mW/°C	
_			

Reduced per 1C at Ta>25°C. Power Dissipation measured when sample mounted on a 70mm×10mm×1.6mm FR4 glass-epoxy PCB (copper area less than 3%)

#### Input / Output Equivalent Circuits



#### Electrical Characteristics (BU4S66G2)

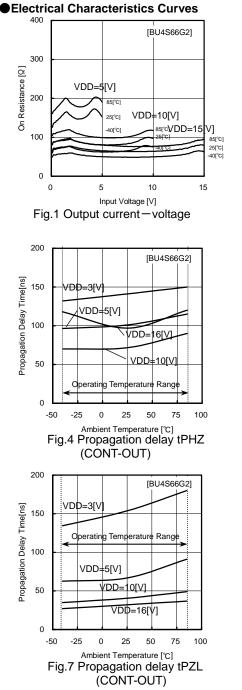
DC Characteristics (Unless otherwise noted : VSS=0[V],Ta=25[°C])

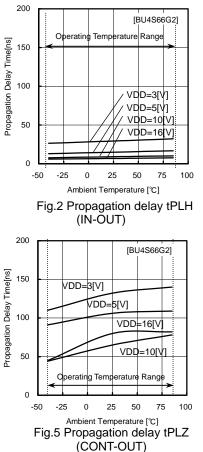
Parameter	Sumbol		Limits		Unit		Condition	Fig.No	
Parameter	Symbol	Min	Тур	Max	Unit	VDD[V]	Condition	1 19.110	
		3.5	—	—		5	Current hetureen in end		
Control "H"input voltage	VIH	7.0	—	—	V	10	Current between in and out=10[µA]	—	
		11.0	—	—		15	οαι-το[μ.(]		
		_	—	1.5		5	Current between in and out		
Control "L"input voltage	VIL		—	3.0	V	10	Current between in and out = 10[µA]	—	
		_	—	4.0		15	_ισ[μ. ι]		
		_	290	950		5	0≦VIN≦VDD		
ON resistance	RON	_	120	250	Ω	10	$RL=10[k\Omega]$	1	
		_	85	160		15			
Channel-OFF	LOFF	_	—	0.3	μA	15	VIN=15[V],VOUT=0[V]	_	
Leakage current	LOIT		—	-0.3	μΛ	15	VIN=0[V],VOUT=15[V]	] —	
		_	—	1.0		5			
Static supply current	IDD		—	2.0	μA	10	VIN=VDD or GND	—	
			—	4.0		15			
Input capacitance(control input)	CC		8	—	pF	—	f=1[MHz]	—	
Input capacitance(switch input)	CS	_	10	-	pF	—	f=1[MHz]	-	

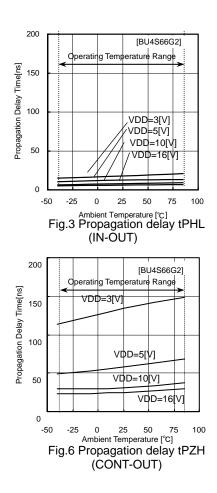
### Switching Characteristics (Unless otherwise noted : VSS=0[V],Ta=25[°C],CL=50[pF])

Parameter	Symbol	Limits			Unit		Fig.No		
Falanletei	Symbol	Min	Тур	Max	Unit	VDD[V]	Condition	Fig.NO	
		_	15	—		5			
	tPLH	_	8	_	ns	10	RL=10[kΩ] CL=50[pF]	2	
Propagation delay time		_	5	_		15			
(I/O→O/I)		—	15	—		5	RL=10[kΩ]		
	tPHL	—	8	—	ns	10	CL=50[pF]	3	
		—	5	—		15			
		—	100	—	-	5	RL=10[kΩ]		
	tPHZ	_	70	-	ns	10	CL=50pF	4	
		_	65	—		15	02-0001		
		—	100	-	+	5	RL=10[kΩ]		
	tPLZ	—	70	—	ns	10	CL=50[pF]	5	
Propagation delay time		—	65	—		15			
(CONTROL→O/I)	tPZH tPZL	—	80	—	ns	5	RL=10[kΩ]		
		—	35	-		10	CL=50[pF]	6	
		—	25	-		15			
		-	80	_	+	5	RL=10[kΩ]		
		_	35	-	ns	10	CL=50[pF]	7	
		—	25	-		15			
	fmax	—	10	_		5	RL=1[kΩ]		
Maximum control frequency	(C)	-	12	_	MHz	10	CL=50[pF]	_	
NA	Fmax	_	12	_	N 41 1-	15	VSS=-5[V],RL=1[kΩ]		
Maximum propagation frequency	(I-O) <sup>*1</sup>	—	30	_	MHz	5	CL=50[pF]	_	
Feedthrough attenuation	FT <sup>*2</sup>	_	600	-	kHz	5	VSS=-5[V],RL=1[kΩ]	-	
Sine wave distortion (1[kHz])	THD <sup>*3</sup>	_	0.05	-	%	5	VSS=-5[V],RL=10[kΩ] CL=50[pF]	-	
		_	200	_	mV	5	RIN=1[kΩ]		
Cross talk (CONTROL→O/I)	CTc	_	400	_	mV	10	ROUT=10[kΩ]	-	
		_	600	_	mV	15	CL=15[pF]		

\*1 Frequency where 20log(VOUT/VIN)=3[dB] \*2 Frequency where 20log(VOUT/VIN)=50[dB] \*1 \*2 \*3 Must be sine wave of VIN±2.5[Vp-p].

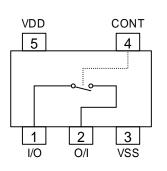






#### ●Pinout Diagram • Pin Description • Input / Output Table

#### Pinout Diagram



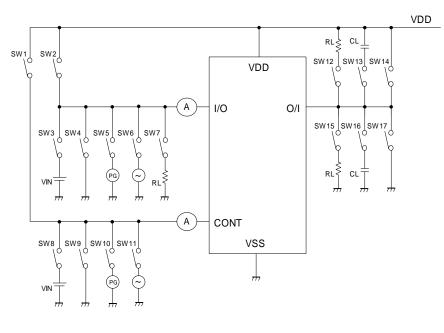
Input / Output Table

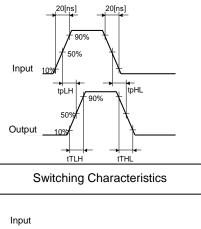
OFF
ON

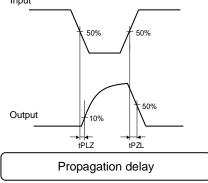
#### **Pin Description**

Pin No	Symbol	I/O	Function
1	I/O	I/O	Analog Switch Input / Output
2	O/I	I/O	Analog Switch Input / Output
3	VSS	_	Power supply(-)
4	CONT	Ι	Control Input
5	VDD		Power supply(+)

#### Measurement Circuit







#### Switching Table

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Paramete	ər	SW 1	SW 2	SW 3	SW 4	SW 5	SW 6	SW 7	SW 8	SW 9	SW 10	SW 11	SW 12	SW 13	SW 14	SW 15	SW 16	SW 17
Input voltage/curre	ent	OFF	ON	OFF	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	ON	OFF	OFF
ON resistance		ON	OFF	ON	OFF	OFF	OFF	OFF	OFF	ON	OFF	OFF						
Channel-OFF		OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF	ON
Leakage curren	t	OFF	OFF	OFF	ON	OFF	OFF	OFF	OFF	ON	OFF							
Switching Charact	eristics	ON	OFF	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	ON	ON	OFF
Propagation time	tPLZ	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF	OFF
CONT→OUT	tPZL	OFF	ON	OFF	ON	OFF	ON	ON	OFF	ON	ON	OFF						
Sine wave distortion	on	ON	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF	OFF	OFF	OFF	ON	ON	OFF
Feedthrough atten	uation	OFF	OFF	OFF	OFF	OFF	ON	OFF	OFF	ON	OFF	OFF	OFF	OFF	OFF	ON	ON	OFF
Control		OFF	OFF	OFF	OFF	OFF	OFF	ON	OFF	OFF	OFF	ON	OFF	OFF	OFF	ON	ON	OFF

#### Notes for use

1. Absolute maximum ratings

An excess in the absolute maximum ratings, such as supply voltage, temperature range of operating conditions, etc., can break down the devices, thus making impossible to identify breaking mode, such as a short circuit or an open circuit. If any over rated values will expect to exceed the absolute maximum ratings, consider adding circuit protection devices, such as fuses.

2. Connecting the power supply connector backward

Connecting of the power supply in reverse polarity can damage IC. Take precautions when connecting the power supply lines. An external direction diode can be added.

3. Power supply lines

Design PCB layout pattern to provide low impedance GND and supply lines. To obtain a low noise ground and supply line, separate the ground section and supply lines of the digital and analog blocks. Furthermore, for all power supply terminals to ICs, connect a capacitor between the power supply and the GND terminal. When applying electrolytic capacitors in the circuit, not that capacitance characteristic values are reduced at low temperatures.

#### 4. GND voltage

The potential of GND pin must be minimum potential in all operating conditions.

5. Thermal design

Use a thermal design that allows for a sufficient margin in light of the power dissipation (Pd) in actual operating conditions.

6. Inter-pin shorts and mounting errors

Use caution when positioning the IC for mounting on printed circuit boards. The IC may be damaged if there is any connection error or if pins are shorted together.

7. Actions in strong electromagnetic field

Use caution when using the IC in the presence of a strong electromagnetic field as doing so may cause the IC to malfunction.

8. Testing on application boards

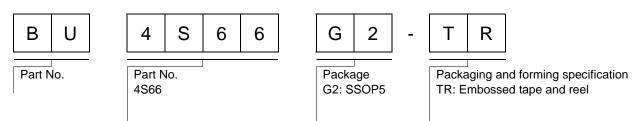
When testing the IC on an application board, connecting a capacitor to a pin with low impedance subjects the IC to stress. Always discharge capacitors after each process or step. Always turn the IC's power supply off before connecting it to or removing it from a jig or fixture during the inspection process. Ground the IC during assembly steps as an antistatic measure. Use similar precaution when transporting or storing the IC.

9. Ground Wiring Pattern

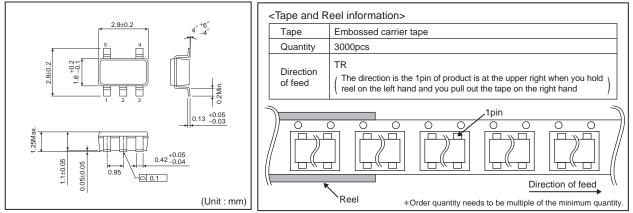
When using both small signal and large current GND patterns, it is recommended to isolate the two ground patterns, placing a single ground point at the ground potential of application so that the pattern wiring resistance and voltage variations caused by large currents do not cause variations in the small signal ground voltage. Be careful not to change the GND wiring pattern of any external components, either.

### BU4S66G2

#### Ordering part number



#### SSOP5



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(Note1) Medical Equipment Classification of the Specific Applications
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JAPAN	USA	EU	CHINA			
CLASSⅢ	CLASSⅢ	CLASS II b				
CLASSⅣ	CLASSII	CLASSⅢ	CLASSⅢ			

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  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation (Pd) depending on Ambient temperature (Ta). When used in sealed area, confirm the actual ambient temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

#### Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used; if flow soldering method is preferred, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
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